

Tflex™ HD90000 Series Thermal Gap Filler



PRODUCT DESCRIPTION

Laird's Tflex™ HD90000 is the latest product in our High Deflection series. Tflex™ HD90000 combines 7.5 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

TflexTM HD90000 is available in thickness from 0.020" (500 μ m) to 0.200" (5000 μ m). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

- 7.5 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress
- Low Outgassing
- Low D3-D20 (< 20ppm)
- Large tolerance applications
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

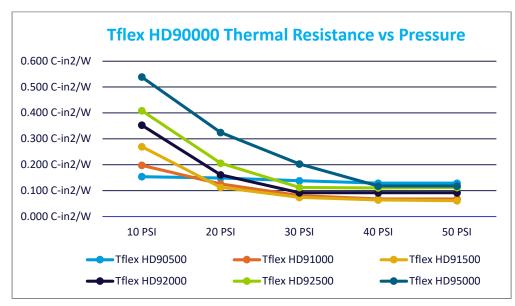
TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	0.020" (500 μm) - 0.20" (5000 μm)	N/A
Thermal Conductivity (W/mK)	7.5	Hot Disk
Density (g/cc)	3.5	Helium Pycnometer
Hardness (Shore 00)	500 and 750 μm: 45	ASTM D2240
	1000 μm and up: 32	
Outgassing TML (weight %)	0.17	ASTM E595
Outgassing CVCM (weight %)	0.01	ASTM E595
Temperature Range	-65°C to 125°C	Laird Test Method
Rth at 40 mils, 10 psi, 50° C	0.198°C–in2/W	ASTM D5470
Dielectric Constant at 1 MHz	8.14	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	8.73×10 ¹³ ohm-cm	ASTM D257

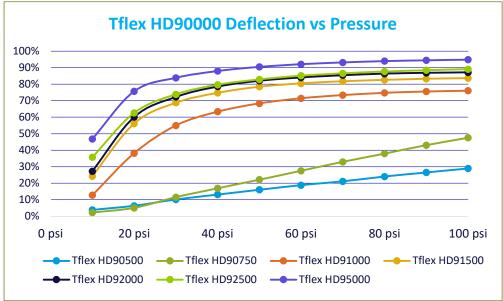
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Tflex™ HD90000 Series

Thermal Gap Filler





AVAILABILITY

STANDARD THICKNESSES

- 0.020" (500 μ m) up to 0.200" (5000 μ m) thick material available in 250 μ m increments
- Available in standard sheet sizes of 18" x 18" (1000 μm and up only) and 9" x 9" or custom die cut parts.

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD90000 indicates Tflex™ HD90000 product line with thickness in microns EXAMPLES:

- Tflex™ HD91000= 1000 µm (0.040") thick Tflex™ HD90000 material
- Tflex™ HD95000= 5000 µm (0.200") thick Tflex™ HD90000 material

A17807-00 Tflex™ HD90000 DS 11102022

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